PZT2907A

PNP Silicon Epitaxial Transistor

This PNP Silicon Epitaxial transistor is designed for use in linear and switching applications. The device is housed in the SOT-223 package which is designed for medium power surface mount applications.

Features

- NPN Complement is PZT2222AT1
- The SOT-223 Package can be Soldered Using Wave or Reflow
- SOT-223 Package Ensures Level Mounting, Resulting in Improved Thermal Conduction, and Allows Visual Inspection of Soldered Joints. The Formed Leads Absorb Thermal Stress during Soldering Eliminating the Possibility of Damage to the Die
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V _{CEO}	-60	Vdc
Collector - Base Voltage	V _{CBO}	-60	Vdc
Emitter – Base Voltage	V _{EBO}	-5.0	Vdc
Collector Current – Continuous	Ι _C	-600	mAdc

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Мах	Unit
Total Device Dissipation (Note 1) $T_A = 25^{\circ}C$	PD	1.5 12	W mW/°C
Thermal Resistance Junction-to-Ambient (Note 1)	R_{\thetaJA}	83.3	°C/W
Lead Temperature for Soldering, 0.0625" from case Time in Solder Bath	ΤL	260 10	°C Sec
Operating and Storage Temperature Range	T _J , T _{stg}	−65 to +150	°C

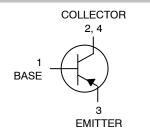
1. FR-4 with 1 oz and 713 mm² of copper area.

ON

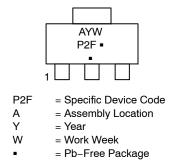
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MARKING DIAGRAM



(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]			
PZT2907AT1G	SOT-223 (Pb-Free)	1,000 / Tape & Reel			
SPZT2907AT1G	SOT-223 (Pb-Free)	1,000 / Tape & Reel			
PZT2907AT3G	SOT–223 (Pb–Free)	4,000 / Tape & Reel			

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

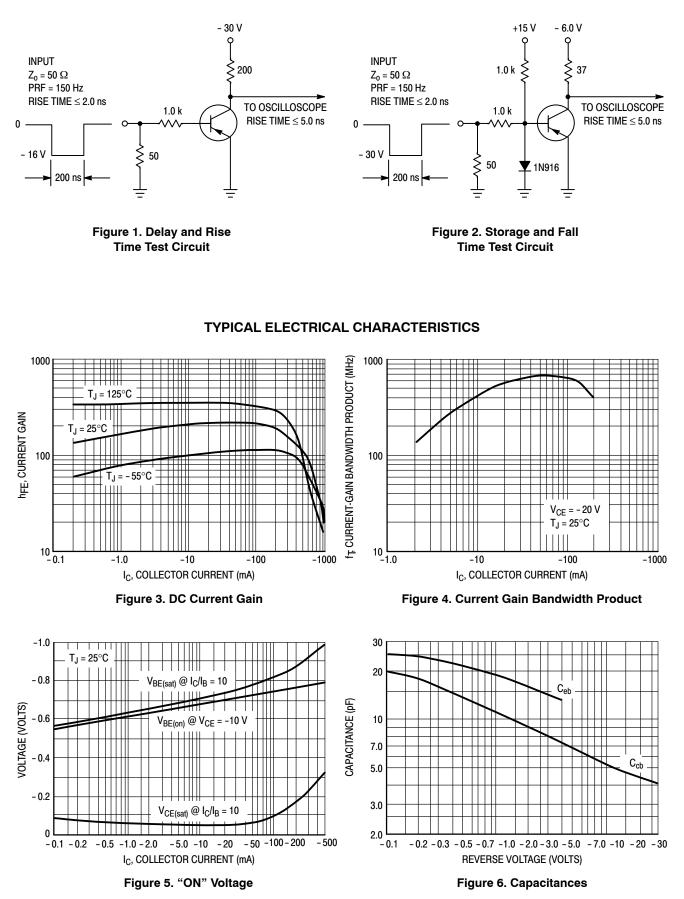
PZT2907A

ELECTRICAL CHARACTERISTICS (T_A = 25° C unless otherwise noted)

Chara	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS				•	-	· ·
Collector-Base Breakdown Voltage $(I_C = -10 \ \mu Adc, I_E = 0)$	V _{(BR)CBO}	-60	-	_	Vdc	
Collector-Emitter Breakdown Volta ($I_C = 10$ mAdc, $I_B = 0$)	ge	V _{(BR)CEO}	-60	-	-	Vdc
Emitter–Base Breakdown Voltage ($I_E = -10 \ \mu Adc, \ I_C = 0$)		V _{(BR)EBO}	-5.0	-	-	Vdc
Collector-Base Cutoff Current $(V_{CB} = -50 \text{ Vdc}, I_E = 0)$		I _{CBO}	-	-	-10	nAdc
Collector–Emitter Cutoff Current ($V_{CE} = -30$ Vdc, $V_{BE} = 0.5$ Vdc)		I _{CEX}	_	_	-50	nAdc
Base-Emitter Cutoff Current (V _{CE} = -30 Vdc, V _{BE} = -0.5 Vdc)	I _{BEX}	_	_	-50	nAdc
ON CHARACTERISTICS (Note	2)	1		1	.1	
DC Current Gain ($I_{C} = -0.1 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}$) ($I_{C} = -1.0 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}$) ($I_{C} = -10 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}$) ($I_{C} = -150 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}$) ($I_{C} = -500 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}$)		h _{FE}	75 100 100 100 50	- - - - -	- - 300 -	-
Collector-Emitter Saturation Voltages ($I_C = -150$ mAdc, $I_B = -15$ mAdc) ($I_C = -500$ mAdc, $I_B = -50$ mAdc)		V _{CE(sat)}	- -		-0.4 -1.6	Vdc
Base-Emitter Saturation Voltages ($I_C = -150 \text{ mAdc}$, $I_B = -15 \text{ mAdc}$) ($I_C = -500 \text{ mAdc}$, $I_B = -50 \text{ mAdc}$)		V _{BE(sat)}	-		-1.3 -2.6	Vdc
DYNAMIC CHARACTERISTIC	S	11		1		
Current-Gain – Bandwidth Product ($I_c = -50$ mAdc, $V_{CE} = -20$ Vdc, f = 100 MHz)		f⊤	200	-	_	MHz
Output Capacitance (V _{CB} = -10 Vdc, I _E = 0, f = 1.0 MHz)		C _c	-	_	8.0	pF
Input Capacitance (V _{EB} = -2.0 Vdc, I _C = 0, f = 1.0 MHz)		C _e	-	-	30	pF
SWITCHING TIMES				•	4	
Turn-On Time		t _{on}	-	-	45	ns
Delay Time	$(V_{CC} = -30 \text{ Vdc}, I_C = -150 \text{ mAdc}, I_{B1} = -15 \text{ mAdc})$	t _d	-	-	10	7
Rise Time	Di	t _r	-	-	40	7
Turn-Off Time		t _{off}	-	-	100	ns
Storage Time	$(V_{CC} = -6.0 \text{ Vdc}, I_C = -150 \text{ mAdc}, I_{B1} = I_{B2} = -15 \text{ mAdc})$	t _s	-	-	80	7
Fall Time		t _f	-	-	30	1

2. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

PZT2907A



DATE 02 OCT 2018





SCALE 1:1

0.10 C

A1



-11

SIDE VIEW

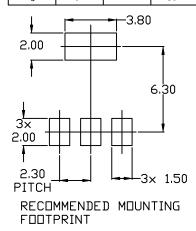
DETAIL A

NDTES:

SOT-223 (TO-261) CASE 318E-04 ISSUE R

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSIONS D & E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.200MM PER SIDE.
- 4. DATUMS A AND B ARE DETERMINED AT DATUM H.
- 5. ALLS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST PDINT OF THE PACKAGE BODY.
- 6. POSITIONAL TOLERANCE APPLIES TO DIMENSIONS 6 AND 61.

	MILLIMETERS			
DIM	MIN.	NDM.	MAX.	
A	1.50	1.63	1.75	
A1	0.02	0.06	0.10	
b	0.60	0.75	0.89	
b1	2.90	3.06	3.20	
с	0.24	0.29	0.35	
D	6.30	6.50	6.70	
E	3.30	3.50	3.70	
e	2.30 BSC			
L	0.20			
L1	1.50	1.75	2.00	
He	6.70	7.00	7.30	
θ	0*		10*	



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SOT-223 (TO-261) CASE 318E-04 ISSUE R

DATE 02 OCT 2018

STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 2: PIN 1. ANODE 2. CATHODE 3. NC 4. CATHODE	STYLE 3: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	STYLE 4: PIN 1. SOURCE 2. DRAIN 3. GATE 4. DRAIN	STYLE 5: PIN 1. DRAIN 2. GATE 3. SOURCE 4. GATE
STYLE 6: PIN 1. RETURN 2. INPUT 3. OUTPUT 4. INPUT	STYLE 7: PIN 1. ANODE 1 2. CATHODE 3. ANODE 2 4. CATHODE	STYLE 8: CANCELLED	Style 9: Pin 1. Input 2. Ground 3. Logic 4. Ground	STYLE 10: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE
STYLE 11: PIN 1. MT 1 2. MT 2 3. GATE 4. MT 2	Style 12: Pin 1. Input 2. Output 3. NC 4. Output	STYLE 13: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR		

GENERIC MARKING DIAGRAM*



- A = Assembly Location
- Y = Year
- W = Work Week
- XXXXX = Specific Device Code
- = Pb-Free Package
- (Note: Microdot may be in either location) *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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